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Fig 3*

1. (Amended) A piezoelectric generator comprising an oscillator package, including a piezoelectric oscillator sealed in a container and electrodes for external connection formed on the surface of the container, and an electronic component mounted integrally on the oscillator package, wherein,

    said container is composed of a multi-layer substrate having a substantially quadrangular shape and having a recess for the storage of the piezoelectric oscillator and a lid member fixed to the multi-layer substrate so as to cover the recess;

    said electrodes for external connection are projecting electrodes each consisting of solder and having a height greater than the mounting height of the electronic component, and are arranged on the surface of the multi-layer substrate on the side opposite the lid member near the four corners thereof; and

    said electronic component is mounted on the same surface of said container that carries the electrodes for external connection thereon.

5. (Amended) The piezoelectric generator according to claim 1, wherein said projecting electrodes are ball-shaped electrodes formed of solder balls.

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13. (Amended) A piezoelectric generator comprising:

    a container including a metallic cap put on the upper surface of a substrate in the form of a quadrangular flat plate, the cap having a skirt portion bonded to the substrate so as to define a space in which a crystal oscillator is to be sealed between the substrate and the cap;

    the crystal oscillator placed on the upper surface of the substrate in the container;

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conceded.

electrodes for external connection arranged on the peripheral portion of the lower surface of the substrate so as to project downward from the lower surface of the substrate; and an electronic component mounted on the lower surface of the substrate; wherein said electrodes for external connection consist of solder and project from the substrate so that the projecting end is in a position below the level of the electronic component mounted on the substrate.

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17. (Amended) The piezoelectric generator according to claim 13, wherein said electrodes for external connection are ball-shaped electrodes formed of solder balls.

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*C3*

20. (Amended) The piezoelectric generator according to claim 5 or 17, wherein the solder balls include a spacer member functioning as a spacer.

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*C4*

27. (New) A piezoelectric generator comprising an oscillator package, including a piezoelectric oscillator sealed in a container and electrodes for external connection formed on the surface of the container, and an electronic component mounted integrally on the oscillator package, wherein,

    said container is composed of a multi-layer substrate having a substantially quadrangular shape and having a recess for the storage of the piezoelectric oscillator and a lid member fixed to the multi-layer substrate so as to cover the recess;

    said electrodes for external connection are projecting electrodes each formed of a conductive material and having a height greater than the mounting height of the electronic

component, and are arranged on the surface of the multi-layer substrate on the side opposite the lid member near the four corners thereof; and

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cont.  
said electronic component is mounted on the same surface of said container that carries the electrodes for external connection thereon;

wherein said projecting electrode is a ball-shaped electrode formed of a solder ball.

28. (New) A piezoelectric generator comprising an oscillator package, including a piezoelectric oscillator sealed in a container and electrodes for external connection formed on the surface of the container, and an electronic component mounted integrally on the oscillator package, wherein,

said container is composed of a multi-layer substrate having a substantially quadrangular shape and having a recess for the storage of the piezoelectric oscillator and a lid member fixed to the multi-layer substrate so as to cover the recess;

said electrodes for external connection are projecting electrodes each formed of a conductive material and having a height greater than the mounting height of the electronic component, and are arranged on the surface of the multi-layer substrate on the side opposite the lid member near the four corners thereof; and

said electronic component is mounted on the same surface of said container that carries the electrodes for external connection thereon;

wherein said electronic component is composed of an IC chip and a capacitor;

wherein said IC chip is mounted substantially on the central portion the multi-layer substrate, said capacitor is mounted adjacent to one side of the IC chip, and an injection area for a sealing resin is provided on the other side of the IC chip.

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cont.

29. (New) The piezoelectric generator according to claim 28, wherein said sealing resin for sealing the IC chip is injected from the side of an area on which the capacitor is not mounted.

30. (New) A piezoelectric generator comprising:

a container including a metallic cap put on the upper surface of a substrate in the form of a quadrangular flat plate, the cap having a skirt portion bonded to the substrate so as to define a space in which a crystal oscillator is to be sealed between the substrate and the cap;

the crystal oscillator placed on the upper surface of the substrate in the container; electrodes for external connection arranged on the peripheral portion of the lower surface of the substrate so as to project downward from the lower surface of the substrate; and

an electronic component mounted on the lower surface of the substrate; wherein said electrodes for external connection are formed of a conductive material and project from the substrate so that the projecting end is in a position below the level of the electronic component mounted on the substrate;

wherein each said electrode for external connection is a ball-shaped electrode formed of a solder ball.

31. (New) A piezoelectric generator comprising:

a container including a metallic cap put on the upper surface of a substrate in the form of a quadrangular flat plate, the cap having a skirt portion bonded to the substrate so as to define a space in which a crystal oscillator is to be sealed between the substrate and the cap;

the crystal oscillator placed on the upper surface of the substrate in the container;

electrodes for external connection arranged on the peripheral portion of the lower surface of the substrate so as to project downward from the lower surface of the substrate; and  
an electronic component mounted on the lower surface of the substrate;  
wherein said electrodes for external connection are formed of a conductive material and project from the substrate so that the projecting end is in a position below the level of the electronic component mounted on the substrate;

wherein the surface of said container is provided with crystal oscillator connection terminals, and through holes formed in the substrate to connect the crystal oscillator connecting terminals and the crystal oscillator are situated in a region where the cap is superposed on and bonded to the substrate.

32. (New) The piezoelectric generator according to claim 27, wherein the solder ball includes a spacer member functioning as a spacer.

33. (New) The piezoelectric generator according to claim 30, wherein the solder ball includes a spacer member functioning as a spacer.